

Part Number: TBA15-11SURKCGKWA

Hyper Red  
Green

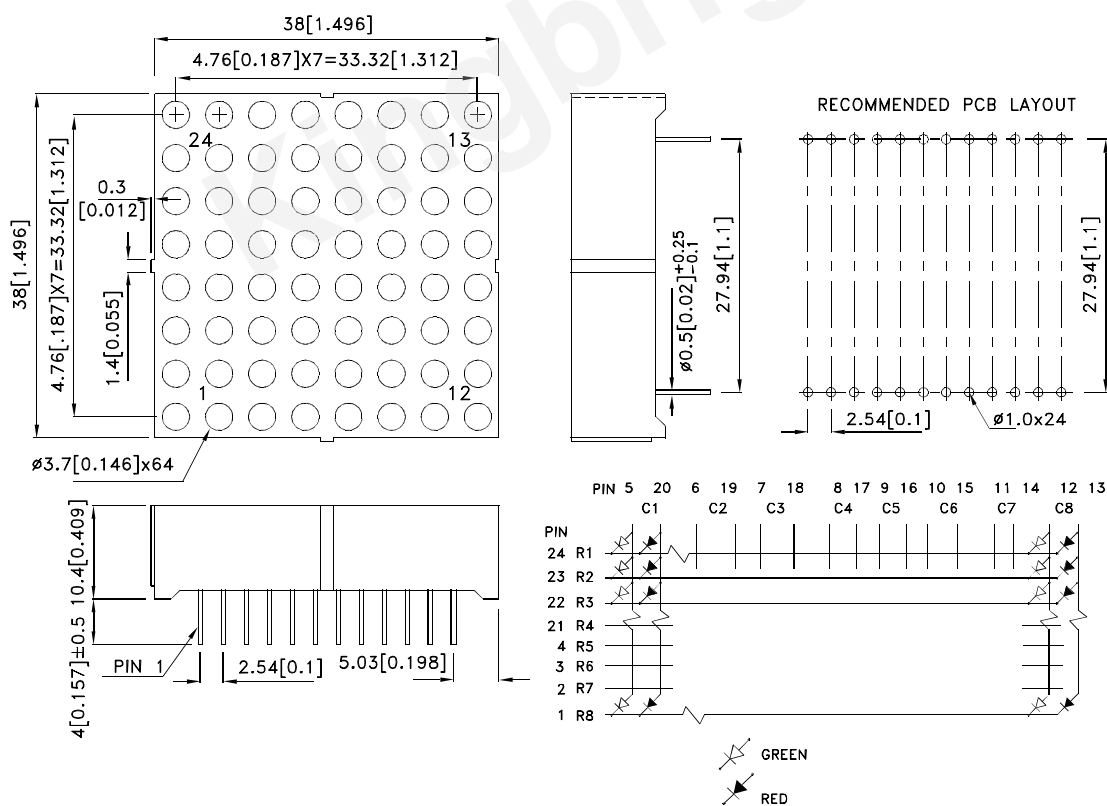
### Features

- 1.5 inch matrix height.
- Dot size 3.7mm.
- Low current operation.
- High contrast and light output.
- Stackable horizontally and vertically.
- Column cathode and column anode available.
- Easy mounting on P.C. boards or sockets.
- Multicolor available.
- Mechanically rugged.
- Standard : gray face, white dot.
- RoHS compliant.

### Descriptions

- The Hyper Red source color devices are made with Al GaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

### Package Dimensions & Internal Circuit Diagram



#### Notes:

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
TBA15-11SURKCGKWA	Hyper Red (AlGaInP)	White Diffused	52000	130000	Column Anode
			*21000	*41000	
	Green (AlGaInP)		21000	54000	
			*9000	*18000	

### Notes:

1. Luminous intensity/ luminous Flux: +/-15%.

\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Hyper Red Green	645 574		nm	I <sub>F</sub> =20mA
$\lambda_D$ [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I <sub>F</sub> =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red Green	28 20		nm	I <sub>F</sub> =20mA
C	Capacitance	Hyper Red Green	35 15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Hyper Red Green		10 10	uA	V <sub>R</sub> =5V

### Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.

3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

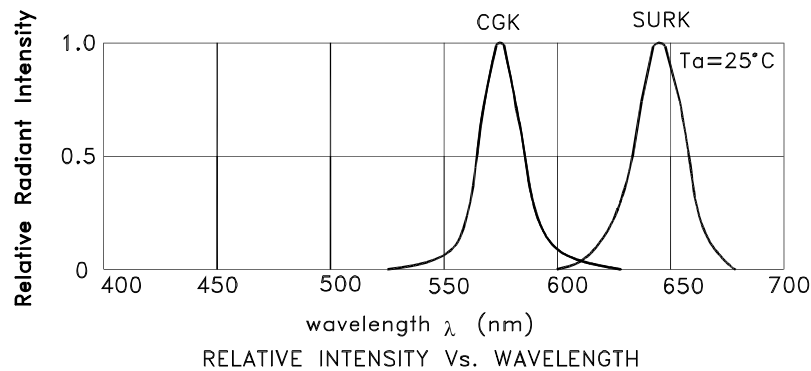
## Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3-5 Seconds		

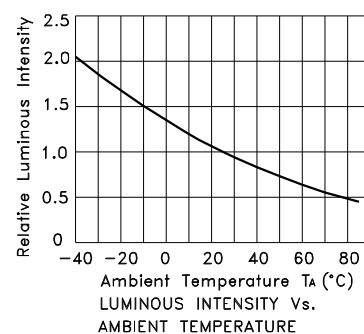
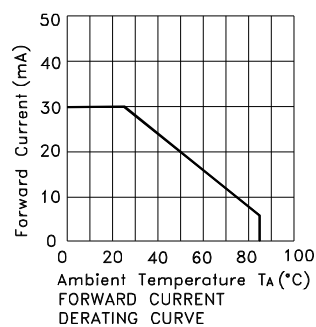
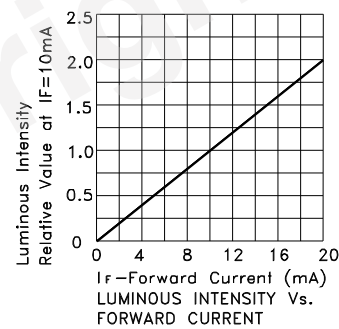
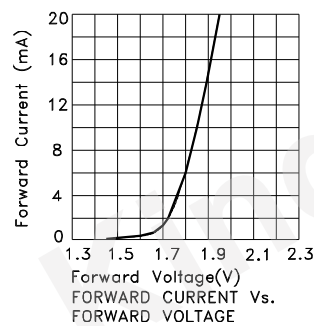
### Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

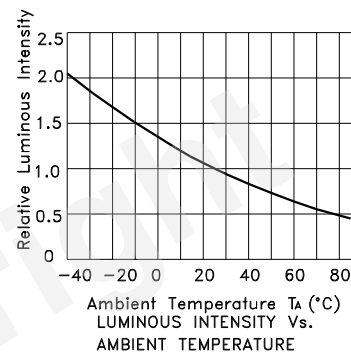
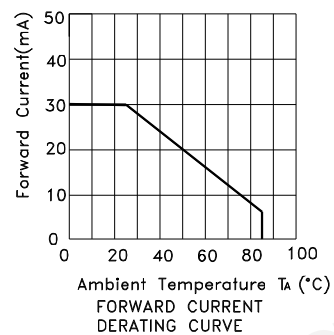
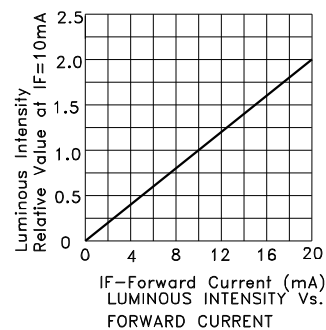
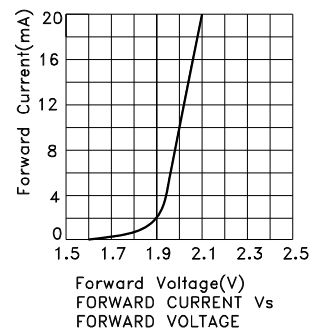
2. 2mm below package base.



**TBA15-11SURKCGKWA**  
**Hyper Red**

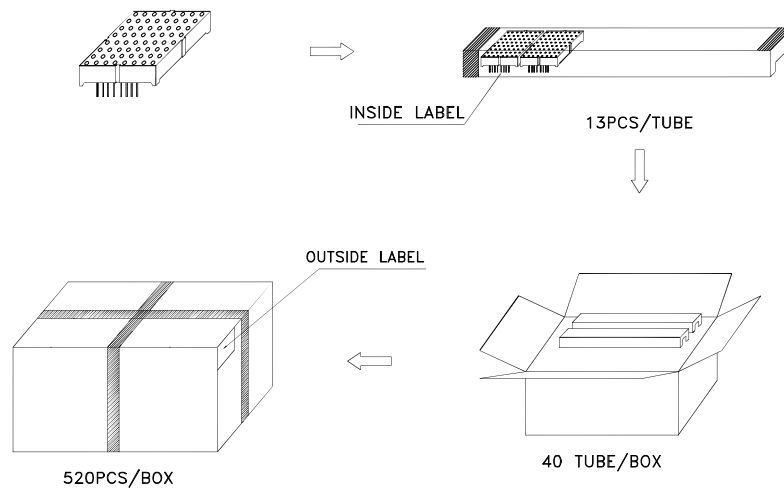


Green



## PACKING & LABEL SPECIFICATIONS

## TBA15-11SURKCGKWA



Inside Label On IC-tube

<b>Kingbright</b>	TYPE: TBx15-11xxx	<div style="border: 1px solid black; border-radius: 50%; padding: 5px; text-align: center;"> <b>PASSED</b>  xx xx xx  <b>FQC</b> </div>	Date
QTY: 13 PCS	CODE: xx		Number OF FQC
XXXXXXXXXX-XXXX		RoHS Compliant	
LOT NO.			

Outside Label On Box

XXXXXX	<div style="border: 1px solid black; border-radius: 50%; padding: 5px; text-align: center;"> <b>PASSED</b>  xx xx xx  <b>FQC</b> </div>		Date
TBx15-11xxx	Bin Code	Number OF QA	
520 PCS	XX	QAx	Date
RoHS Compliant			

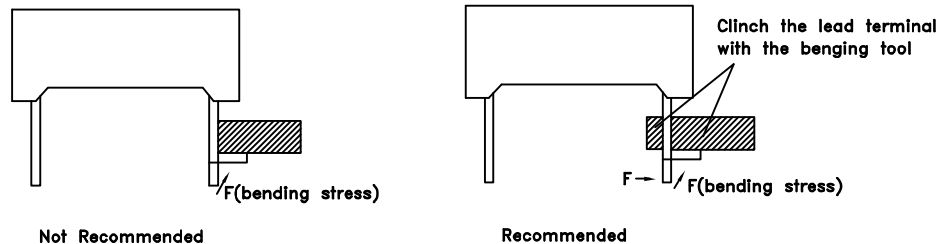
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## THROUGH HOLE DISPLAY MOUNTING METHOD

### Lead Forming

Do not bend the component leads by hand without proper tools.  
The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

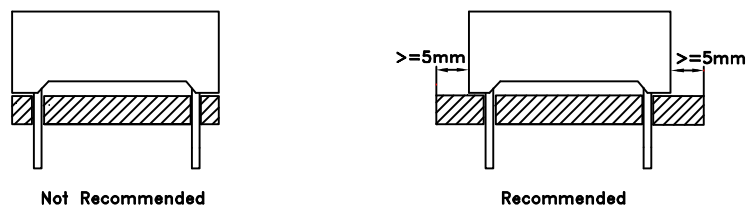


### Installation

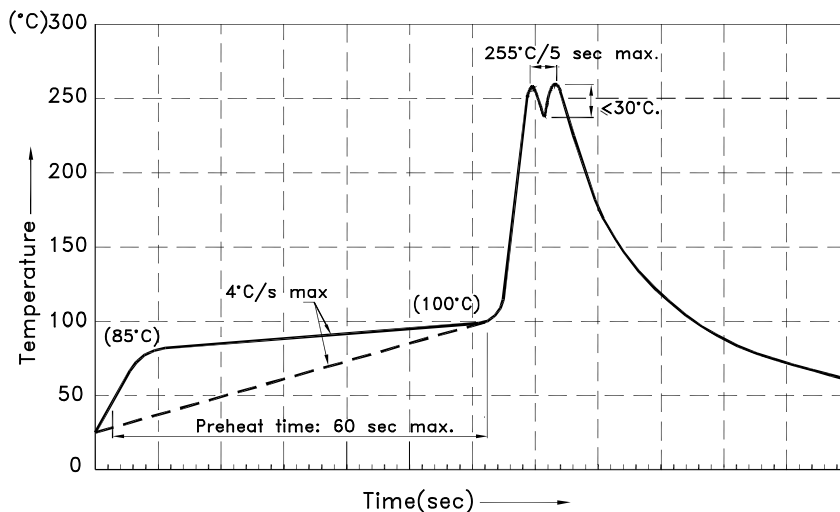
1. The installation process should not apply stress to the lead terminals.
2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



## Recommended Wave Soldering Profiles:



### Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.
7. During wave soldering, the PCB top-surface temperature should be kept below 105°C.

## Soldering General Notes:

1. Through-hole displays are incompatible with reflow soldering.
2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

## CLEANING

1. Mild "no-clean" fluxes are recommended for use in soldering.
2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts. And the devices should not be washed for more than one minute.

## CIRCUIT DESIGN NOTES

1. Protective current-limiting resistors may be necessary to operate the Displays.
2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.

